



General description

GBLC05C-SL a 5V bi-directional TVS diode, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making his device an ideal solution for protecting voltage sensitive high-speed data lines. The GBLC05C-SL has a low capacitance with a typical value at 1.0pF, and complies with the IEC61000-4-2(ESD) standard with $\pm 30\text{KV}$ air and $\pm 30\text{KV}$ contact discharge. It is assembled into a leadfree SOD-323 package. The small size, low capacitance and high ESD surge protection make GBLC05C-SL an idea choice to protect cell phone, wireless systems, and communication equipment.

Features and benefits

- Ultra Low Capacitance 0.6 pF(Typ)
- 300W peak pulse power (8/20 μs)
- Working Voltage 5V
- Low leakage current: nA Level
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 30\text{KV}$
 - Contact discharge: $\pm 30\text{KV}$
 - IEC61000-4-5 (Lightning) 18A (8/20 μs)
 - IEC61000-4-4 (EFT) 80A (5/50nS)
- RoHS compliant

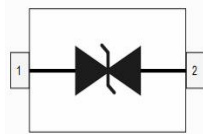
Application information

- High- speed data lines
- Smart phones
- USB Ports
- Wireless Systems
- Ethernet 10/100/1000 Base T

Ordering information

Par Number	Package	Packaging	Reel Size
GBLC05C-SL	SOD323	3000/Tape & Reel	7 inch

Schematic & Pin configuration

Simplified outline	Graphic symbol
	

Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise specified)

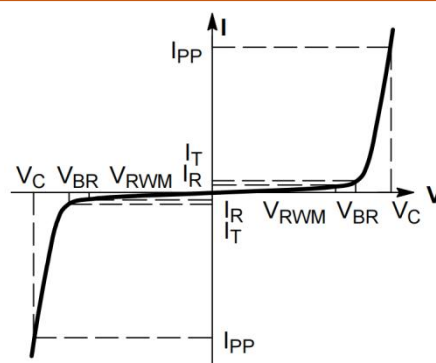
Parameter	Symbol	Value	Unit
Peak Pulse Power ($t_p = 8/20\mu\text{s}$)	P_{pk}	300	W
Peak Pulse Current ($t_p = 8/20\mu\text{s}$)	I_{pp}	18	A
ESD voltage IEC 61000-4-2 (air discharge)	V_{ESD}	30	KV
ESD voltage IEC 61000-4-2 (contact discharge)	V_{ESD}	30	KV
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$
Operating Temperature Range	T_{OP}	-40 to +85	$^\circ\text{C}$

Electrical Characteristics ($T_A = 25^\circ\text{C}$, unless otherwise specified)

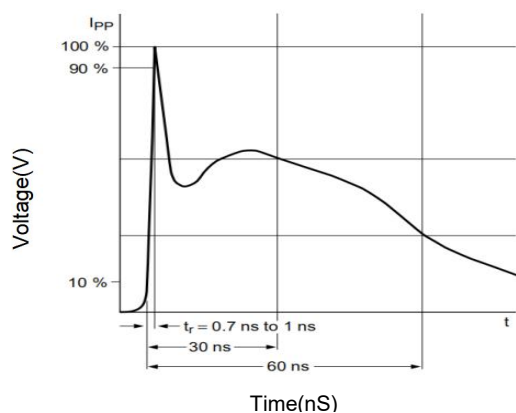
Parameter	Symbol	Min	Typ	Max	Unit	Condition
Reverse Working Voltage	V_{RWM}	--	--	5.0	V	
Breakdown Voltage	V_{BR}	6.0	7.2	8.0	V	$I_T = 1\text{mA}$
Leakage Current I_{Leak}	I_R	--	--	0.1	μA	$V_{RWM} = 5\text{V}$
Clamping Voltage	V_C	--	8.5	--	V	$I_{pp} = 5\text{A}$, $T_p = 8/20\mu\text{s}$
Clamping Voltage	V_C	--	15.0	16.5	V	$I_{pp} = 18\text{A}$, $T_p = 8/20\mu\text{s}$
Junction Capacitance	C_J	--	0.6	0.9	pF	$V_R = 0\text{V}$, $f = 1\text{MHz}$

Portion Electronics Parameter

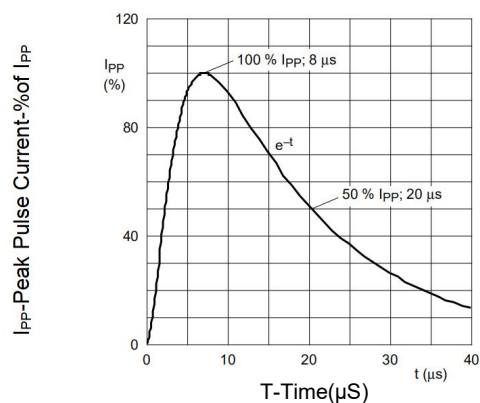
Symbol	Parameter
I_{pp}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{pp}
V_{RWM}	Working Peak Reverse Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	V_{BR} Test Current



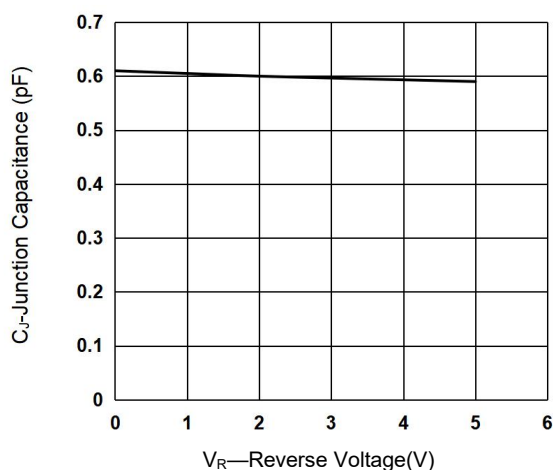
Typical Performance Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise Specified)



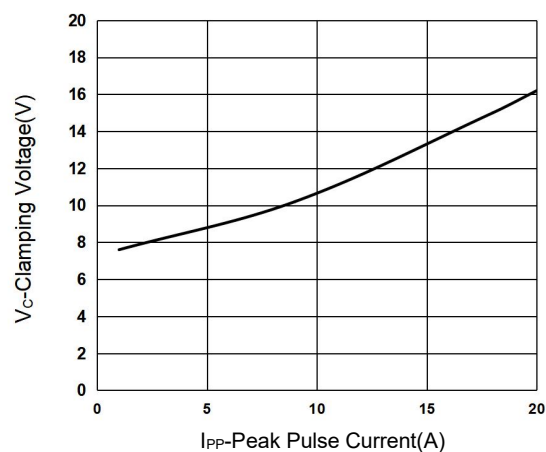
IEC61000-4-2 Pulse Waveform



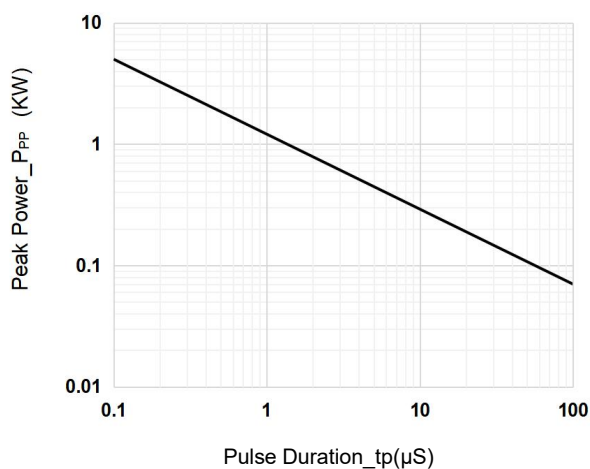
IEC61000-4-5 8X20 μs Pulse Waveform



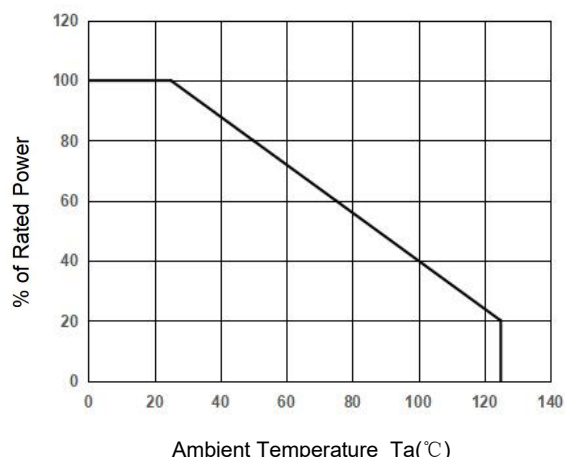
Junction Capacitance vs. Reverse Voltage



Clamping Voltage vs. Peak Pulse Current



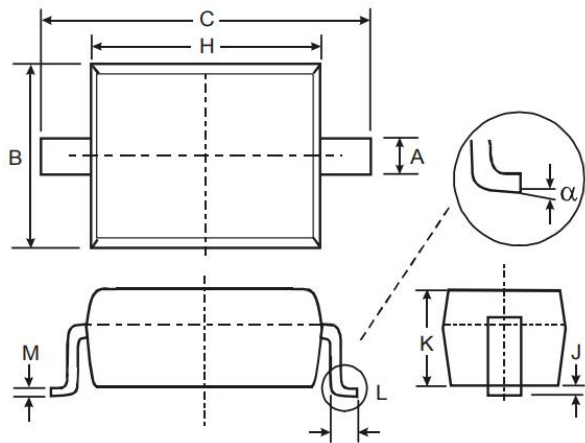
Peak Pulse Power vs. Pulse Time



Power Derating Curve

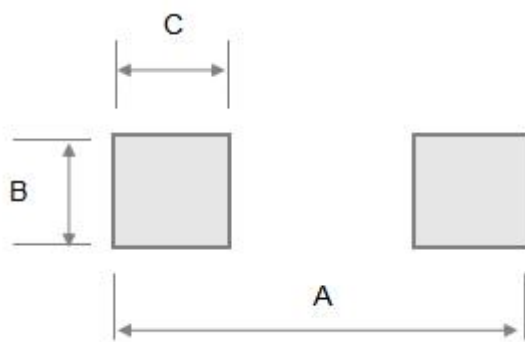
Package Outline Dimensions (mm)

SOD323



SYMBOL	DIMENSIONS	
	MIN	MAX
A	0.25	0.40
B	1.20	1.40
C	2.35	2.75
H	1.50	1.80
J	0.01	0.15
K	0.75	1.05
L	0.20	0.40
M	0.08	0.25
α	0°	8°

Soldering Footprint (mm)



SYMBOL	DIMENSIONS
A	3.20
B	0.80
C	0.80